







The V850 Series[™] of embedded microcontrollers answers diversified needs in all kinds of application systems. It realizes lower power consumption and noise while achieving higher performance and multiple functions. Consisting of a rich lineup, the V850 Series offers optimum solutions for next-

generation embedded systems.

Inverter-type air conditioners



Digital video cameras



Automotive electronics





Digital still cameras



Cellular phones



Storage devices

Pamphlet U15412EJ1V0PF

Fax machines

2





Network modems



Microwave ranges



Washing machines



Digital video recorders





Home audio



Vending machines



Electronic music instruments



Car audio

Pamphlet U15412EJ1V0PF



Car AV centers

V850 POSITION



V850 OROADMAP



Pamphlet U15412EJ1V0PF

INDEX

5KEYS V850	06
Architecture	18
Variety of Peripheral Functions	27
Low Power & Low Noise	32
Middleware	36
Flash Memory Microcontrollers	38
Functional Outline	42
Comfortable Development Environment	53
Information	61





5KEYS V850





Scalable coverage of 20 MHz to over 00 MHz

- 3 to 4 times higher performance at same frequency compared to 16-bit microcontrollers
- V850, V850ES, and V850E1 cores are upward compatible at object level.
- V850 Series covers a broad range from middle to high-end market with a single instruction set







From low-end/high-end general-purpose products all the way to ASSP lineup

- Low-end lineup designed for 8/16-bit market (V850ES, V850/Sxx)
- High-end lineup with on-chip MEMC, DMA, that pursues high performance (V850E)
- ASSP lineup with on-chip dedicated hardware optimized for various fields (V850E, V850ES, V850/Sxx)





Enriched middleware lineup

- Rich lineup of middleware related to video, audio, networks, etc., optimized for the V850
- Realization of peripheral functions through V850 + middleware combination
 - \rightarrow Shorter development time, lower system cost







High-performance CPU cores

 By meeting the five conditions consisting of leading-edge process technology, high-performance CPU cores, a rich lineup of IP cores, a top-down design environment, and a flexible application environment, the V850 Series offers optimum system-on-chip solutions.







Rich lineup and high operability

neni

len

- Inherits operability of 78K Series.
- Shorter software development TAT through superior operability and sophisticated development environment
- Easy C-language support through high-performance CPUs and real-time OS embedding possible



V850E Product Development Concept

Pursuit of high performance

High-performance CPU using V850E core

- 10% higher performance than V850 CPU at same frequency
- 10% to 20% higher code efficiency than V850 CPU through addition of C-compatible instructions
- Upward compatibility at object level with V850 CPU cores

Enhanced external bus performance

On-chip direct interface for various memories

- SRAM, page ROM, EDO DRAM, synchronous DRAM, etc.
- On-chip DMA controller
 - Realization of voluminous data processing and high-performance control on one chip





V850E Product Features

V850E/MS1

- Performance of 43 MIPS @ 33 MHz
- On-chip memory controllers for EDO DRAM, etc.
- Lineup of products for 5 V systems and 3.3 V systems

V850E/MS2

Support of 5 V interface enables connection of existing external I/Os
 Contributes to higher cost performance of sets through use of V850E CPU architecture

V850E/MA1

High performance of 62 MIPS @ 50 MHz

On-chip memory controllers for SDRAM, etc.

Various peripheral functions such as timer, serial interface, and A/D converter

V850E/MA2

On-chip SDRAM controller

Contributes to smaller applications, lighter weight, and higher cost performance through use of 14 × 14 mm, 100-pin package

V850E/IA1

 On-chip 3-phase sine wave PWM timer, 2-phase encoder input up/down counter, A/D converter, 2-system motor driving enabled through inverter control
 6-system serial I/F including FCAN for automotive LAN (Ver. 2.0 Part B compliant)

V850E/IA2

 2-system motor driving enabled through on-chip peripheral functions almost the same as those of V850E/IA1

System can be configured with single 5 V power supply thanks to on-chip regulator









Application example using V850E/MA2





V850ES, V850/Sxx Product Development Concept





V850ES, V850/Sxx Product Features

V850ES/SA2, SA3

- Ultra-low power consumption/high-speed operation (30 mW @ 2.5 V, 17 MHz)
- Low-voltage operation of 2.2 V Min. (1.8 V under planning)
- On-chip single power supply flash memory
- On-chip V850ES core

V850/SA1

- Ultra-low power consumption (66 mW (20 MHz @ 3.3 V, mask ROM version, Typ.))
- Rich memory lineup (ROM 64 KB to 256 KB/RAM 4 KB to 8 KB)
- Support of CSP package (121-pin FBGA)

V850/SV[·]

- Various on-chip peripheral functions including servo timer
- Rich memory lineup (ROM 192 KB to 384 KB/RAM 8 KB to 16 KB)
- Support of high-pin-count CSP package (180-pin FBGA)
- ASSP lineup for DVC

V850/SB1, SB2

- Low EMI noise
- On-chip large-capacity memory (512 KB/24 KB Max.)
- Rich memory lineup (ROM 128 KB to 512 KB/RAM 12 KB to 24 KB)
- Automotive bus support (V850/SB2 only)

V850/SF1

- Low EMI noise
- On-chip FCAN controller (2 ch Max.)
- ASSP lineup for car audio

V850/SC1, SC2, SC3

- Low EMI noise
- Enhanced peripheral functions for V850/SB1, SB2 (100-pin 144-pin)
- Automotive bus support (IEBus, FCAN)







V850ES, V850/Sxx Product Features

*: Under development

Smooth transition from CISC to RISC

CISC-like use enabled

- Bit manipulation instructions (SET1, CLR1, NOT1, TST1)
- Multi-status flags

0

• 32-bit barrel shifter

On-chip standard peripheral functions of 78K Series

- Timers (8-bit, 16-bit)
- Serial interface (3-wire CSI, UART)
- Watchdog timer, etc.

High code efficiency

- Equals CISC code efficiency (1.0 to 1.2)
- High-level language (C language) programming supported

Comparison of peripheral functions of 78K Series and V850/Sxx products

	78K/0 Series	78K/IV Series			V850 Series		
	µPD78003x	µPD78421x	V850/SA1	V850/SB1,2	V850/SV1	V850/SF1	V850/SC1,2,3
16-bit timer	TMO	+	+	+	+	+	+
8-bit timer	TM5	←	←	+	←	+	-
Serial interface (CSI)	SIO3	+	+	+	+	+	+
Serial interface (UART)	UART0	+	UART3	+	+	+	+
I ² C interface	IIC0	+	←	+	+	←	+
AD converter	ADCTL0	+	+	+	+	+	+
Real-time output	-	RT00	←	+	+	-	-
Watchdog timer	WDT	Separate specifications	WDT	+	+	←	+
Watch timer	WT	+	+	WTN0	+	+	+
Key return function	-	Separate specifications	-	KR0	+	+	+
							←:Listed on left

- :Not provided

V850 ASSP Lineup



■V850E/IA2 inverter air conditioner application example



■V850/SB2 System Block Diagram (Car Audio)



■V850/SV1 System Block Diagram (DVC)





Memory Lineup

And in case of the local division of the loc





Package Lineup

Package Name	Applicable Products
100-pin plastic QFP (14 \times 20 mm)	V850/SB1, SB2, SF1
100-pin plastic LQFP (14 \times 14 mm)	V850E/MA2, MS2, IA2, V850ES/SA2, V850/SA1, SB1, SB2, SF1, V853
144-pin plastic LQFP (20 \times 20 mm)	V850E/MA1, IA1, MS1, V850/SC1, SC2, SC3
176-pin plastic LQFP (24 × 24 mm)	V850/SV1
121-pin plastic FBGA (12 × 12 mm)	V850ES/SA3, V850/SA1
157-pin plastic FBGA (14 $ imes$ 14 mm)	V850E/MS1
161-pin plastic FBGA (13 × 13 mm)	V850E/MA1
180-pin plastic FBGA (13 × 13 mm)	V850/SV1

QFP package photos



100-pin plastic QFP 0.65 mm pitch, 14 \times 20 mm, 3.0 mm thick

• FBGA package photos



121-pin plastic FBGA 0.8 mm pitch, 12 \times 12 mm, 1.48 mm thick



100-pin plastic LQFP 0.5 mm pitch, 14 \times 14 mm, 1.4 mm thick



144-pin plastic LQFP 0.5 mm pitch, 20×20 mm, 1.4 mm thick



176-pin plastic LQFP 0.5 mm pitch, 24 \times 24 mm, 1.4 mm thick



157-pin plastic FBGA 0.8 mm pitch, 14 \times 14 mm, 1.31 mm thick



161-pin plastic FBGA 0.8 mm pitch, 13 \times 13 mm, 1.48 mm thick



180-pin plastic FBGA 0.8 mm pitch, 13 \times 13 mm, 1.48 mm thick



The Eco Symbol mark is applied to products that comply with NEC's environmental standard, which is one of the world's toughest. Such products are antimony-free and use smaller amounts of halogen, and are subject to product assessment and green procurement.





V850 Common Architecture

The V850 Series, which consists of single-chip RISC microcontrollers that use an architecture optimized for embedding, has the following features.

5-stage pipeline processing	Harvard architecture	32 general-purpose registers	Simple addressing	2-byte basic instruction set
Support of CISC-like instructions	Multi-status flags	DSP function	32-bit barrel shifter	

■5-stage pipeline processing

The V850 Series uses a 5-stage pipeline structure (5 stages from instruction fetch to writeback) that supports simultaneous processing of 5 instructions, thus enabling the execution of almost all instructions in just one clock.



Harvard architecture

The V850 Series uses the Harvard architecture, which is designed so that the instruction bus and data bus can operate completely independently from each other, thereby preventing pipeline operation problems and ensuring efficient instruction execution.





■32 general-purpose registers

The V850 Series provides 32 general-purpose registers. Along with a hardware environment that is ideal for program execution, the development environment, including compilers, exploits these 32 registers to achieve program generation with superior code efficiency and execution performance.



For example, looking at the program execution time and code size changes when the number of registers used by the compiler is changed using the servo control module, we can see that the larger the number of registers, the better the program execution speed and the smaller the code size. However, from about 26 registers, the improvement in terms of execution speed and code size becomes smaller, and in the neighborhood of 32 registers, there are no more changes. This is why the V850 Series has been provided with 32 registers as the strict minimum requirement.

Software register bank

The number of registers can be selected from among 22, 26, and 32 as a compiler option to efficiently execute application programs. Unused registers can be used as a software register bank for which save and restore processing is not required during interrupt servicing or task switching, which increases the processing speed.



- ① Save the program counter, etc., to a save register.
- ② Execute the interrupt restore instruction. Restore the program counter value, etc., from the save register.
- ③ Save general-purpose registers to stacks.
- ④ Restore general-purpose registers from stacks.

General-purpose register configuration

31 0			
r0 Zero Register	Name	Application	Operation
r2 r3 Stack Pointer(SP)	rO	Zero register	Always holds "0"
r4 Global Pointer(GP) r5 Text Pointer(TP) r6	r1	Assembler reservation	Used as working register for address generation
17 18 19 10 110 111 112	r2	Address/data variable register (If real-time OS being used does not use r	
r13 r14 r15	r3	Stack pointer	Used for stack frame generation during function call
r17 r18 r19	r4	Global pointer	Used when accessing global variables in the data area
120 121 122 123 124 125	r5	Text pointer	Used as register for specifying the beginning of the text area (program code allocation)
r26 r27 r28	r6-r29	Address/data var	iable register
ISO Element Pointer(EP) IS1 Link Pointer(LP) 31 0 PC Program Counter	r30	Element pointer	Used as base pointer for address generation during memory access
	r31	Link pointer	Used during function call by compiler
	PC	Program counter	Holds instruction addresses during program execution

System register configuration

	No.	System		System Operand Specification		erand fication	Application
		Register Name	LDSR	STSR			
	0	EIPC	0	0	Register for saving status		
	1	EIPSW	0	0	during interrupt		
	2	FEPC	0	0	Register for saving status		
	3	FEPSW	0	0	during NMI		
	4	ECR	×	0	Interrupt source register		
	5	PSW	0	0	Program status word		
(16	CTPC	0	0	Register for saving status			
nly supported by	17	CTPSW	0	0	during CALLT execution		
B50E1 CPU	18	DBPC	0	0	Register for saving status		
pre products	19	DBPSW	0	0	during exception/debug trap		
	20	CTBP	0	0	CALLT base pointer		
6-15, 21-31	Reserved	×	×				
	× : Access pro	phibited LDSR:	Instructio contents	on to load to syste	d general-purpose register m register		
	○ : Access enabled STSR			on to stor purpose	e system register contents to register		

0



Simple addressing

The increased amount of address calculations in the CPU in the case of complex addressing causes disturbances in the pipeline operation. As a result, address calculation becomes a bottleneck for pipeline processing and raising the frequency to increase the performance becomes difficult. The V850 Series avoids this problem by supporting only simple addressing.



Addressing mode

Instruction addresses





Operand addresses

Register addressing

Addressing that accesses the general-purpose register specified by the general-purpose specification field or a system register as an operand.

Immediate addressing

Addressing of 5-bit data or 16-bit data for manipulation in the instruction code.



16-bit displacement (disp16)

that has been sign extended

to word length as the

operand address.



lation

■2-byte basic instruction set

The V850 Series employs a 2-byte instruction code to perform basic processing to enable compact program development equivalent to 16-bit CISC microcontrollers.







CISC-like instructions for embedding (bit manipulation instructions)

The V850 Series supports bit manipulation instructions suitable for flag manipulation on I/O registers, which play a large role in embedding control.

- Improvement of operability of memory mapped I/ Os for control purposes
- Manipulation of any 1 bit of byte data in the memory space
- Provision of test (tst1)/set (set1)/clear (clr1)/invert (not1)
- Effective for reducing object size and execution time since flags can be manipulated in 1-bit units with 1 instruction

Example: Setting (1) bit 6 of ASIM00 register				
Bit Manipulation	When Used	When	Used	
Coding example	set1 6, ASIM00[r0]	ld.b ASIM00[r0], r20 ori 0x0040, r20, r20 st.b r20, ASIM00[r0]	add -4, sp] Save r20 Id.b ASIM00[r0], r20 ori 0x0040, r20, r20 st.b r20, ASIM00[r0] Id.w 0[sp], r20 add 4, sp] Restore r20	
Object size	4 bytes	12 bytes	24 bytes	
Execution time	4 clocks	4 clocks	8 clocks	

Multi-status flags

In the V850 Series, calculation results are reflected in registers as status flags. As a result, delay branching such as can be seen in the RISC microcontrollers of other manufacturers does not occur and programs can be coded with the same feel as CISC microcontrollers.

- · Easy recording with assembler
- Improved object efficiency and execution speed

Example: Program that branches to positive/negative/zero according to register contents

	CISC Microcontroller		V850		Other Manufacturer's RISC Microcontroller	
ZERO : Zero processing PLUS : Positive processing MINUS : Negative processing	cmp jz jgt jmp	ax, 0 ZERO PLUS MINUS	cmp bz bgt br	0, r10 ZERO PLUS MINUS	cmp/eq bt cmp/pl bt bra nop	#0, r10 ZERO r10 PLUS MINUS ;For delay branching

DSP function

The V850 Series provides a DSP function for executing high-speed calculations and product-sum operations indispensable for digital signal processing such as image and speech processing.

- Direct data handling via general-purpose registers
- Realization of digital signal processing through generalpurpose CPU
- High-speed 16-bit (V850 CPU), 32-bit (V850E1 CPU) multiply/sum-of-products
- (Multiply: 1 to 2 clocks, sum-of-products: 3 clocks)
- · Effective for filter operations and matrix operations for feedback calculations in speed, position, and other servo control.



32-bit barrel shifter

V850 Series can realize bit manipulations frequently used during signed data and image data processing in 1 instruction per clock.

- Shifting of any number of bits (0 to 31) executable in 1 instruction per clock Improved execution speed/object efficiency Effective for extracting arbitrary bit lengths of image data and signed data
- (extracting code during MH/MR/MMR encoding, etc.)



Strengths of V850E1 and V850ES Cores

The V850E1 and V850ES cores are CPU cores that enhance the functions of the V850 core.

■ V850E1 core

- •Higher performance and improved operating frequency of 50 to 100 MHz
- Improved external memory access function
- Improved code efficiency (10 to 15% higher than V850 core)
 Addition of C language compatible instructions (Switch instruction, CALLT instruction, etc.)
- •High performance high-end lineup (V850E products), system-on-chip core lineup

■ V850ES core

- Next-generation CPU core of low-end lineup
- •Support of lower voltage for V850/Sxx products
- Improved code efficiency through use of same architecture as V850E1
- (10 to 15% higher than V850 core)

CPU Core Function	V850	V850ES	V850E1
Maximum operating frequency	20/33 MHz	20 MHz	50→100MHz
Maximum program memory space	16 MB	16 MB	64 MB
Maximum data memory space	16 MB	16 MB	256 MB
	Use of 5-stage pipeline Use of Harvard architecture Non-blocking load/store Parallel execution of instructions (during instruction er internal ROM) • Addition of branch/load pipes • Shift to 3-operand manipulations in 1 slot		s (during instruction execution in s in 1 slot
Higher code efficiency	Use of 2-byte instructions Use of CISC instructions	Addition of C language compatible (Addition of Switch instruction, Cal instruction, Prepare/Dispose instru	instructions It instruction, data conversion ction)
Multiplier	16 × 16 bit→32 bit	16×16 bit $\rightarrow 32$ bit (32-bit multiply instruction support)	32×32 bit $\rightarrow 64$ bit
Interrupt responsiveness	11 to 18 clocks	4 to 10 clocks	

Pamphlet U15412EJ1V0PF



Employment as ASIC CPU Cores

Smooth transition to ASIC microcontroller development using V850E1 CPU cores

- 1. Introduction to market with short TAT through use of standard V850E1 products
- 2. Optimization of system through switch to ASIC
- Easy securing of compatibility from traditional systems made into ASICs through use of same device development methods for both standard products and ASIC microcontrollers

Development of CPU cores bearing in mind shift to ASIC

Software debugging support

Release of CPU core that supports on-chip debugging through full-function in-circuit emulator, JTAG method (N-Wire ICE) and on-chip debugging with trace function

N

> Internal system bus configuration

Independent high-speed 32-bit synchronous system bus and 16-bit asynchronous bus for low-speed peripheral function macro connection, realizing

both high-speed processing, low-power consumption and easy design

Provision of large assortment of peripheral function macros

Cache memory, memory controller, ROM/RAM, USB, etc.

◆ Covering required performance and power consumption through support of a large variety of processes

Process	Cell-based IC family
0.35 <i>µ</i> m	CB-9VX
0.25 <i>µ</i> m	CB-10VX
0.13 <i>µ</i> m	CB-12

■V850E1 core

- Realization of excellent performance/power ratio of 827 MIPS/W for 100 MHz Max. (at 2.5 V operation)
- Improved object efficiency
- A flexible and high-performance bus system can be configured through independent buses such as a high-speed system bus that enables 400 MB/s data transfer and a low-speed peripheral macro connection bus.
- Support of on-chip debugging function

■V850E1 core



■V850E/MA1 block configuration





■V850E1, V850ES architecture

The V850E1 and V850ES cores achieve high performance and higher code efficiency through the implementation of the following improvements to the V850 CPU core.

Non-blocking load/store

Addition of branch/load pipe

· Parallel execution of instructions

2-clock branching

Shift to 3-operand manipulations in 1 s

of mov + add

Non-blocking load/store

Improved absolute performance
 Improved absolute performance

Conventional (V850 CPU) Pipeline is stopped until MEM stage complete

- Example: Synchronous processing
- Improved code efficiency
- 10 to 15% improvement in object
- efficiency mainly when C compiler used

Improved bus use efficiencyShorter interrupt insensitivity period

Pipeline configuration



Addition of branch/load pipes

•Pipeline operation with branch instruction



MEM (external memory) Load ID WB IF ΕX instruction ADD ID (MEM) WB IF EX instruction Next IF ID FX MEM WB instruction Effective pipeline processing that uses the Async WB Pipeline when V850E1 CPU appropriate, according to the instruction Load MEM (external memory) IF ID ΕX WB instruction T1 T2 ADD IF ID ΕX WB DF instruction Next IF ID ΕX MEM WB instruction

•Parallel instruction execution (when executed by internal ROM)



* The next branch instruction code is also fetched due to the internal 32-bit bus.

•Shift to 3-operand manipulations in 1 slot





Addition of high-level language compatible instructions

The V850E1 and V850ES cores have enhanced the instruction set of the V850 core as follows.

- switch (2 bytes)
 - C language switch statement processing converted into instruction
- callt (2 bytes)/ctret (4 bytes)
 - Table-reference branching
 - Reducing size of call code that frequently appears
- Data conversion instructions (2 bytes)
 - char, short type cast executed with 1 instruction
 - sxh, sxb, zxb, and zxh instructions
- prepare/dispose (4 bytes)
 - Function start/end processing executed in 1 instruction

- unsigned Load
 - Reduction of unsigned manipulation code
- mov imm32, reg (6 bytes/2 clocks)
- Reduction of address setting code
- ♦ mul/mulu (4 bytes)
 - · Reduction of array address calculation
 - · Improvement of sum-of-products performance
- ♦ Other
 - Bit manipulation (register indirect bit specification)
 - cmov (Conditional Move), divide (div/divu/divhu)
 - sasf, endian conversion





callt N (Table-reference subroutine calling)





Middleware Performance

■Measurement conditions

.

Common	
CPU	: V850 core (33 MHz)
	Measurement results are frequency-converted values (50 MHz).
Bus width	: 16 bits
Number of waits	:1
	(The basic bus cycle is 3 clocks, so 1 bus cycle = 4 clocks.)
Compiler	: CA850
Tool	: V850 in-circuit emulator (IE) (product of NEC)





V850 MMR Method — A4 100 dpi





JPEG

Internal ROM	: Program
Internal RAM	: Stack, work area (one part)
External memory (SRAM)	: Data and remaining work area
Data I/O	: RGB

•MH/MR/MMR

- Internal ROM
 - : Program
- External memory (SRAM) : Encoding/decoding table, change point table, stacks (including I/O parameters)

JBIG

- Internal ROM
- : Program (including probability assumption table (1 KB))
- External memory (SRAM) : Learning table, stacks (including I/O parameters)





V850 JPEG Method

		Processing Time					
Sample ratio	QVGA(32	0×240×24)	VGA(640×480×24)				
Sample Tatio	Compression	Decompression	Compression	Decompression			
4 : 1 : 1 (Quality75)	0.27s	0.21s	1.09s	0.85s			
4 : 2 : 2 (Quality75)	0.33s	0.26s	1.33s	1.04s			

Pamphlet U15412EJ1V0PF



Variety of Peripheral Functions

Memory Access Functions

SDRAM controller

Products: V850E/MA1, MA2

- ◆ SDRAM connectable without external circuit
- CAS latency: 2, 3 supported
- CBR refresh, CBR self refresh supported



Note The address signal used differs depending on the SDRAM product.

■DMA controller (provided in V850E products)

Products: V850E/MA1, MA2, MS1, MS2, IA1, IA2

- Transfer targets: Memory-peripheral I/O, memory-memory
- Single, single step, block transfer
- ♦ 8-/16-bit data units
- Transfer type: 1-cycle transfer, 2-cycle transfer
- Number of transfers: 65,536 Max.



DRAM controller

Products: V850E/MS1, MS2, MA1

- ◆ EDO DRAM directly connectable without external circuit
- 2CAS type DRAM supported
- CBR refresh, CBR self refresh supported



DMA controller (provided in V850/Sxx products)

Products: V850/SA1, SB1, SB2, SV1, SF1, SC1, SC2, SC3

- ◆Transfer targets: Internal RAM-on-chip peripheral I/O
- ♦ Single transfer
- 8-/16-bit data units
- ◆Transfer clock: 4 clocks Min.
- ♦Number of transfers: 256 Max.





Multi-stage buffer type

Products: V853, V850/SV1, V850E/MA1, IA1, IA2, MS1

- Conversion can be started by both software and hardware
- Eight conversion result registers are incorporated
- Select/scan modes can be switched



Select mode operation



■Scan mode



Analog input

Conversion result registers



onversion result register

ANI7

 \bigcirc



Timer/Counter Functions

■24-bit servo timer

Product: V850/SV1

- ♦ 24-bit timer unit for servo control
- Capture registers: 4
- Compare registers: 2
- External input detector with 1-64/1-128 divider



■3-phase inverter control timer

Products: V850E/IA1, IA2

- ♦ 3-phase PWM output function
- Symmetric triangular wave, asymmetric triangular wave, sawtooth wave Interrupt culling function
- Culling rate: 1/1, 1/2, 1/3, 1/4, 1/8, 1/16
- ◆ 3-phase PWM forcible output stop function
- Real-time output function



■PWM

- Product: V850/SV1
- ◆ 12- to 16-bit PWM output
- Main pulse + additional pulse configuration Main pulse: 4/5/6/7/8 bits
- Additional pulse: 8 bits
- ◆ Active level of PWM output pulse selectable



■Up/down counter

Products: V850E/IA1, IA2

- ◆ 16-bit 2-phase encoder input supported
- Compare registers: 2
- Capture/compare registers: 2





Serial Interface

■Variable-length serial interface

- Products: V850/SB1, SB2, SV1, SF1, SC1, SC2, SC3 ♦ 3-wire serial I/O
 - Data length switchable between 8 bits and 16 bits
 - Start bit switchable between MSB and LSB



■IEBus controller

- Products: V850/SB2, SC2
 - Supports communication mode 1
 - Maximum number of transfer bytes: 32 bytes/frame
 - Maximum transfer speed: Approx. 17 Kbps



■8-/16-bit serial interface

- Products: V850/SC1, SC2, SC3, V850E/IA1, IA2
 - ♦ 3-wire serial I/O
 - Data length switchable between 8 bits and 16 bits
 - Start bit switchable between MSB and LSB



Products: V850E/IA1, V850/SF1, SC3

- ◆ CAN protocol Ver. 2.0 Part B
 - (Transmission/reception of standard and extended frames)
- Maximum transfer rate: 1 Mbps
- 32 message buffers



Note The number of channels differs depending on the product.



Distinctive Peripheral Functions of V850

■Watch timer

- Products: V850/SB1, SB2, SV1, SC1, SC2, SC3
 - ♦ 0.5-second interrupt generation using watch timer function
 - Interval timer supported

■Hsync/Vsync separator

- Product: V850/SV1
 - Separation of Vsync (vertical) signal and Hsync (horizontal) signal from decoding sync signal of VCR
- Odd/even field discrimination

ROM correction operation





ROM correction function

Products: V850/SB1, SB2, SV1, SF1, SC1, SC2, SC3

- Substitutes JMP r0 instruction for instruction of address to be corrected and branches to 0000H
- Program can be modified following creation of mask ROM
- ◆ Correction addresses: 4 points





Low Power & Low Noise

Low Power Consumption Measures

Low-power-consuming, high-speed microcontrollers are required for portable devices and battery-operated devices such as DVCs and cellular phones. The V850 Series incorporates various functions to lower the power consumption.

Superior power performance

The V850ES and V850/Sxx products feature a thorough power-saving design that realizes a superb power/performance ratio of 1.1 to 0.7 mA/MIPS. As a result, these products realize a low consumption current only one fifth that of a 16-bit CISC microcontroller of comparable performance. By featuring such extremely high power performance, these products enable the simultaneous realization of lower power consumption and more sophisticated functions in various systems.



Clock gear function

The V850/Sxx products come with two oscillators: a main clock and a subclock. 1/1/, 1/2, 1/4, or 1/8 of the main clock or the subclock^{Note} can be selected as the CPU operating clock, making it possible to minimize the power consumption according to the system's operating status. **Note** Not selectable in V850/SV1



Function to cut voltage between A/D converter VREF and resistor string

Voltage application to the A/D converter's resistor string can be switched on and off. The power consumption can be minimized by switching off voltage application to the resistor string when the A/D converter is not used.

Main products:

V850/SB1, SB2, SC1, SC2, SC3, SF1

Standby mode

An efficient low-power-consumption system can be realized by using the three standby modes, STOP, IDLE, and HALT, according to the usage purpose.







EMI Countermeasures

Minimizing the influence of electromagnetic interference (EMI) from the microcontroller in AV equipment such as car audio systems is a major requirement, making the reduction of EMI one of the highest technological priorities for microcontroller manufacturers. Various EMI countermeasures are implemented in the V850 Series.

EMI countermeasures for individual chip

Noise reduction measures focussing on the following three points are implemented as noise countermeasures in individual V850 Series chips.

- ◆ Reduction of noise generation
 - Use of low-voltage internal logic power supply
 - Optimization of oscillator
- Reduction of noise propagation
 - Separation of internal logic sound source and power supply of pins
 - Reduction of cross talk between different power supply wires
- Confining of noise inside
- On-chip decoupling capacitor between power supply and GND inside microcontroller
- Separation of power supply and GND for oscillator



Standardization of evaluation methods (1/2)

There are no rules regarding the EMI measurement testing method for individual microcontrollers. NEC aims to standardize evaluation circuit constants through the use of a standalone EMI evaluation board and evaluate products in a measuring environment that uses a shielded room and power supply filters. This approach enables the evaluation of different products (8-bit and 16-bit NEC CISC microcontrollers, etc.) in the same environment.

Standalone EMI evaluation board



Standalone EMI evaluation board measurement environment





Standardization of evaluation methods (2/2)

•EMI evaluation results

A comparison of the EMI evaluation results for Phase 2 products (V850/SB1 A products) and Phase 4 products (V850/SF1) is shown below.



Remark Oscillation frequency = 16 MHz

Evaluation of characteristics using radio system board (1/2)

In addition to EMI measurement using a standalone EMI evaluation board, NEC has also established an evaluation method employing set evaluation criteria using a radio system board. Since the evaluation results obtained with the radio evaluation board match the evaluation method established by the customer, the influence of EMI can be judged directly.

Radio system board



Radio system board measurement environment





Evaluation of characteristics using radio system board (2/2)

•Radio system board block diagram



CPU board block diagram



•Results of characteristics evaluation using radio system board

The EMI reduction efficiency can be ascertained with a radio system board in the same way as standalone microcontroller evaluation.



Remark fxx : Oscillation frequency

Pamphlet U15412EJ1V0PF



Middleware Development System

NEC is developing a range of middleware products suitable to processors for various systems. NEC middleware is realized by original NEC technology, superior thirdparty technology, and established standards.



JPEG

Conforms to JPEG international standard

- Conforms to DCT baseline process (non-reverse coding)
- Versatile compression and decompression processing

<Compression functions>

- User-customizable VRAM input module
- · User-specified Huffman and quantization tables
- APPn marker insertion
- Compression suspend function
- <Decompressing processing>
- User-customizable VRAM output module
- Support of various JPEG markers (DRI, RSTn, DNL)
- Decompressing suspend function

JPEG Performance g Time Pre QVGA (320×240×24 CPU Sample Ratio VGA (640×480×24) Compression Decompre Decompr V850E/MS1 (33MHz)^{Note} 4:1:1 (Quality75) 0.32s 0 249 1.3s 0.97s Programs are placed in internal ROM, and stack and work areas (one part) are placed in internal RAM. Data and the remaining work area are placed in external RAM.

Memory

R	MC	RAM			
Compression	Decompression	Compression	Decompression		
10KB	7.5KB	5KB	10KB		



V850 Series Speech Recognition

The V850 Series uses internal memory and peripheral I/Os to realize speech recognition on one chip. This makes this series ideal for applications that require speech recognition in sets with large constraints, such as games and home appliances.

- Speech recognition realized using just the internal memory and peripheral I/Os of V850 Series
- Increased number of recognized words

Number of recognized words: 30 (for V850/SA1, 20 MHz)





• Speech recognition evaluation system

In introducing speech recognition, NEC has provided an environment that allows easy evaluation.

For details about this system or how to purchase it, contact NEC.





Handwriting Recognition (Japanese Only)

- Easy to use because of flexibility regarding stroke order and count Pattern matching method based on "non-linear normalization matching method" Conversion of pen-drawn lines into image
- High recognition rate, high-speed recognition Recognition of 95% or higher in 0.1 s (V85x: 25 MHz)
- Support of up to JIS No. 2 standard
- JIS No. 1 Standard: Approx. 3,400 characters, JIS No. 2 Standard: Approx. 800 characters
- New characters can be added (pictographs, etc., can be freely added)

A dictionary can be created from character data using a dictionary compilation tool.

ROM/RAM Description Capacity ROM Approx. 60 KB Program Dictionary data (approx. 4,200 characters) Approx. 450 KB Approx. 60 KB Data RAM Work area Approx. 32 KB Stack area Approx. 2 KB

Text to Speech (TTS) (For Japanese Text)

- Speech synthesized from Japanese Kana and Kanji texts (SJIS code)
- Versatile speech synthesis Synthesis of male and female voices (2 types)
 - Various parameters such as intonation and reading speed can be adjusted.
- TTS rhythm data (pitch, phoneme duration) can be designed (Support of Speech Designer)
- TTS using natural rhythm possible (synthesis of more natural sounding speech) • Support of characters with special readings (character readings
 - can be set using the user dictionary)

Synthesis speed (V853: 25 MHz)

Speech: Between 1.9 s^{Note} and 3 s; Text analysis: 163 ms; speech generation: 1.709 ms

Note Varies depending on the input character string.

ROM/RAM	Description	Capacity
ROM	Program data	Approx. 103 KB
	Dictionary data (approx. 80,000 words)	Approx. 1.2 MB
	Phoneme data	Approx. 670 KB to 1.4 MB
RAM	Work area	Approx. 160 KB
	Stack area	Approx. 256 KB
	Speech output buffer	Approx. 8 KB \times n blocks

Middleware Product List

Middleware list

			1/050 Q 1
Category	Mide	V850 Series	
Image	MH/MR/MMR		0
	JBIG		0
	JPEG		0
Speech	Text To Speech	Japanese	0
	Speech CODEC	G.726 (ADPCM)	0
Recognition	Speech recognition	Japanese (small vocabulary)	O
	Speech recognition	English (US) (small vocabulary)	0
	Handwriting recognition Japanese (input frame re		0
Internet	Browser		0
	TCP/IP		0
Drivers	IrDA protocol stack		0
	USB		\bigtriangleup
	IEEE1394		0
	PCMCIA/CF card	0	
	PC-compatible file system	0	
Other	Font		0

- Remarks 1. ◎: Development completed; ○: Under development; △: In planning
 2. Third-party products included.
 3. For detaits about middleware products, refer to the following http://www.ic.nec.co.jp/apsoft/english/middle_top.html

Middleware performance

Middleware	Performance	Power(MIPS)	ROM	RAM
MH/MR/MMR	MH Chart1 : Enc0.12s/Dec0.08s	-	64 KB	200 bytes
JBIG	Chart1 : Enc0.73s/Dec0.83s	-	21 KB	2.6 KB
JPEG	QVGA × 24 : Enc0.32s/Dec0.24s	-	17.5 KB	15 KB
G.726(ADPCM)	32Kbps, 16Kbps	Enc8/Dec8.2	9 KB	80 bytes
Speech recognition (small vocabulary)	0.4s	19 (20 words)	82 KB	3.5 KB
		63 (100 words)		(15 words)
Handwriting recognition	0.1s/character	14	570 KB	34 KB
(Japanese, input frame required)				
IrDA protocol stack		-	60 KB	16 KB

Flash Memory Microcontrollers

Features

To answer the need for shorter development time and maintenance after shipping, NEC offers microcontrollers with on-chip flash memory available in a large range of capacities from 128 KB to 512 KB as part of the V850 Series. NEC's flash memory microcontrollers offer the following features.

- Support of batch rewrite of entire memory and rewrite in area units
- Flash memory programming with self-rewrite in area units
- Support of on-board programming through serial communication using a flash memory programmer
- Erase/write voltage: 2.5 V, 7.8 V, 10.3 V

Flash Memory Size (Bytes)	12	8K		256K		384K	512K
RAM Size (Bytes)	4K	6K	8K	10K	16K	16K	24K
V850E/MA1				0			
V850E/IA1				0			
V850E/IA2		0					
V850E/MS1	0						
V853	0		0				
V850/SA1	0		0				
V850/SV1					0	0	
V850/SB1					0		0
V850/SB2					0		0
V850/SF1					0		
V850/SC1							0
V850/SC2							0
V850/SC3							0
V850ES/SA2*					0		
V850ES/SA3*					0		

*: Under development

Rewrite Mode

The V850 Series supports a programmer rewrite mode that uses serial communication supporting on-board programming, as well as a self-programming mode that rewrites flash memory with user programs, to enable continuous use from development to maintenance.

Programmer rewrite mode



Self-Programming Mode

Flash memory can be erased and rewritten by calling a selfprogramming function (device-internal processing) using a selfprogramming interface, from a program placed in an area other than the flash memory. The self-programming function is called by switching from the normal operation mode to the selfprogramming mode using the flash programming mode control register (FLPMC).





Specifications

Part No.	Flash Memory	Power Supply	Max. Operating	Package	Package Rewrite		Rewrite Voltage Rewrite Mode			
	Capacity	Voltage	Frequency		VDD	VPP				
V850E/MA1	256 KB	3.0 to 3.6 V	50 MHz	144-pin LQFP (20 $ imes$ 20mm)	3.3 V	7.8 V	CSI, HS-compatible CSI	100		
				161-pin FBGA (13 × 13mm)						
V850E/IA1	256 KB	3.0 to 3.6 V (Internal unit)	50 MHz	144-pin LQFP (20 × 20mm)	3.3 V	7.8 V	CSI, UART, HS-compatible CSI	100		
		4.5 to 5.5 V (External pin)								
V850E/MS1	128 KB	3.0 to 3.6 V	33 MHz	144-pin LQFP (20 × 20mm)	3.3 V	7.8 V	CSI, UART, HS-compatible CSI	100		
				157-pin FBGA (14 × 14mm)						
	128 KB	3.0 to 3.6 V (Internal unit)		144-pin LQFP (20 × 20mm)						
		4.5 to 5.5 V (External pin)								
V853	128 KB	4.5 to 5.5 V	33 MHz	100-pin LQFP (14 × 14mm)	5 V	10.3 V	10.3 V	CSI, UART, HS-compatible CSI	20	
	256 KB	-		100-pin LQFP (14 × 14mm)						
V850/SA1	128 KB	3.0 to 3.6 V	20 MHz	100-pin LQFP (14 × 14mm)	3.3 V	7.8 V	7.8 V	CSI, UART, HS-compatible CSI	100	
	256 KB	-		100-pin LQFP (14 × 14mm)						
				121-pin FBGA (12 × 12mm)						
V850/SV1	256 KB	3.1 to 3.6 V	20 MHz	176-pin LQFP (24 × 24mm)	3.3 V	7.8 V	CSI, UART, HS-compatible CSI	100		
				180-pin FBGA (13 × 13mm)						
	384 KB			180-pin FBGA (13 × 13mm)						
V850/SB1	256 KB	4.0 to 5.5 V	20 MHz	100-pin LQFP (14 × 14mm)	3.3 V 7.8 V	3.3 V 7.8 V	/ 7.8 V C	7.8 V CSI, UART, HS-compatible CSI	CSI, UART, HS-compatible CSI	100
				100-pin QFP (14 × 20mm)						
	512 KB			100-pin QFP (14 × 20mm)						
V850/SB2	256 KB	4.0 to 5.5 V	13 MHz	100-pin LQFP (14 × 14mm)	3.3 V	7.8 V	CSI, UART, HS-compatible CSI	100		
				100-pin QFP (14 × 20mm)						
	512 KB			100-pin QFP (14 × 20mm)						
V850/SF1	256 KB	4.0 to 5.5 V	16 MHz	100-pin LQFP (14 × 14mm)	3.3 V	7.8 V	CSI, UART, HS-compatible CSI	100		
				100-pin QFP (14 × 20mm)						
V850/SC1, SC2, SC3	512 KB	4.0 to 5.5 V	20 MHz	144-pin LQFP (20 × 20mm)	3.3 V	7.8 V	CSI, UART, HS-compatible CSI	100		
V850ES/SA2*	256 KB	2.3 to 2.7 V	17 MHz	100-pin LQFP (14 × 14mm)	2.5 V	2.5 V	CSI, UART	100		
V850ES/SA3*	256 KB	2.3 to 2.7 V	17 MHz	121-pin FBGA (12 × 12mm)	2.5 V	2.5 V	CSI, UART	100		

* : Under Development

Flash Memory Programmers

■NEC flash memory programmer (PG-FP3)

[Features]

- ♦ Supports write to all NEC microcontrollers with dual-power supply flash memory
- Device-specific information required for writing can be automatically set with parameter files.
- Supports both on-board writing and program adapter writing.
- ♦ Easy-to-carry A5 size
- Simple operation either on standalone basis or with a dedicated application (Flashpro III) on Windows[™] 95, 98, 2000, or Windows NT[™] Ver. 4.0
 <Standalone>

Executed in one of the following modes: PROMLOAD, ERASE, PROGRAM, VERIFY, E.P.V.

<On Windows>

Operated via GUI screen.



Third-party flash memory programmers (1/2)

•Programming system Y1000-8

[Manufacturer/Marketing] Wave Technology Co., Ltd.

[Target Devices] V850E/MA1, V850/SV1

[Features]

- Gang programmer enabling simultaneous programming and verification of up to 8 devices
- Enables reading of master data directly from floppy disk to internal memory.
- Data dump display and editing functions
- Master data storable on internal hard disk
- Emphasizes simple and comfortable operation via touch panel and workability via PASS/FAIL display, check-sum display, and task count display supporting sockets

[Additional information]

TEL: +81-3-5304-1885 FAX: +81-3-5304-1886 E-mail: sales@y1000.com Website: http://www.y1000.com/en/index.html

Flashpro III FL-PR3

[Manufacturer/Marketing] Naito Densei Machida Mfg. Co., Ltd. [Target Devices] V850 Series

[Features]

- Supports writing to all NEC microcontrollers with dual-power supply flash memory
- Device-specific information required for writing can be automatically set with parameter files.
- Supports both on-board writing and program adapter writing.
- ♦ Easy-to-carry A5 size
- Simple operation either on standalone basis or with a dedicated application (Flashpro III) on Windows 95, 98, 2000, or Windows NT Ver. 4.0

[Additional Information]

FAX: +81-45-475-4091

E-mail: info@ndk-m.co.jp

Website: http://www.ndk-m.co.jp/eng/index.html







Third-party flash memory programmers (2/2) •NET IMPRESS

[Manufacturer/Marketing] Yokogawa Digital Computer Corporation [Target Devices] V850E/IA1, V850/SB1 (µPD70F3033A) [Features]

This in-circuit programmer for flash memory microcontrollers (NET IMPRESS) is used to program the microcontrollers with on-chip flash memory of each company, which have various writing specifications, while solder mounted on the user system board.

This programmer comes in four models (AF220, AF210, AF120, AF110) to be used according to the intended application field.

• One control module is the key to this product's versatility.

Microcontrollers of the same family are supported by changing parameters, and microcontrollers of different families are supported by purchasing the license for the descriptor part.

◆ Can be used on standalone basis as well as via a host machine.

Rich lineup of freeware

[Additional Information]

TEL : Japan	+81-42-333-6224						
U.S.A	+408-244-1932						
Europe	+44-1256-811998						
FAX : Japan	+81-42-352-6109						
U.S.A	+408-244-1881						
Europe	+44-1256-811761						
E-mail : info@advice.ydc.co.jp							
Website : http://www.ydc.co.jp/micom/index_E.htm							



Flash Memory Programmers

NEC's flash memory programmer (PG-FP3) supports all NEC microcontrollers with dual-power-supply on-chip flash memory. The PG-FP3 stores the device-specific information required for rewriting in a parameter file and the rewriting environment for each microcontroller can be automatically set by downloading this file. After the parameter file is downloaded, the PG-FP3 can be used on a standalone basis. Combined with a program adapter (FA series (manufactured by Naito Densei Machida Mfg. Co., Ltd.)), this programmer can be used to write single microcontrollers. On-board writing is also possible using a target cable. An example of the rewriting environment when using the program adapter is described below.

•Example of rewriting environment



- ① Flash memory programmer (PG-FP3)
- 2 Target system
- ③ Power supply unit
- ④ Host machine interface (RS-232-C)
- 5 To host machine

Cautions 1. Install the control software of the PG-FP3 and the parameter file of the target device in the host machine.

- PG-FP3 control software: Provided with PG-FP3
- Parameter files: Distributed via online delivery
- 2. In addition to using the program adapter, rewriting can also be done on-board on the target system.

Functional Outline

							(1/11)
	V850E/MA1					V850E/MA2	
lt	em	μPD703103A	μPD703105A	μPD703106A	µPD703107A	μPD70F3107A	μPD703108
CPU core		V850E1	ł	I			V850E1
CPU performance (I	Ohrystone)	-	62MIPS (@ 50 MHz)				-
Internal ROM		None	128 KB (Mask ROM)		256 KB (mask ROM)	256 KB (flash memory)	None
Internal RAM		4 KB			10 KB	1	4 KB
External	Address bus	26 bits					25 bits
bus interface	Data bus	16 bits					16 bits
	Programmable waits	0 to 7					0 to 7
Interrupt sources		External: 25 (17) ^{Note} Internal: 33					External: 8 (4) ^{Note} Internal: 23
DSP function	32×32→64	0.02 to 0.04µs (@ 50 MH	lz)				0.025 to 0.05µs (@ 40 MHz)
	32×32+32→32	0.06μs (@ 50 MHz)					0.075µs (@ 40 MHz)
	16×16 <i>→</i> 32	-					—
	16×16+32→32	-					-
Timer/counter (RPU)		16-bit timer/event counter 16-bit interval timer × 4 ch	16-bit timer/event counter \times 2 ch 16-bit interval timer \times 4 ch				
Serial interface	CSI	1 ch	-				
(SIO)	CSI/I ² C	-	-				
	CSI/UART	2 ch	2 ch				
	UART	1 ch	-				
	Dedicated BRG	3 ch					2 ch
A/D converter		8 ch (10-bit resolution)	4 ch (10-bit resolution)				
DMA controller		4 ch	4 ch				
Real-time output po	rt	-					-
Ports	I/O	106					74
	Input	9					5
Other peripheral I/O functions		Memory access control fr (SDRAM, SRAM, EDO D PWM: 2 ch (8/9/10/12-bit	Memory access control function (SDRAM, SRAM, page ROM, etc., directly connectable)				
Power save function		HALT, IDLE, STOP	HALT, IDLE, STOP				
Operating frequency	/	4 to 50 MHz	4 to 40 MHz				
Power supply voltage		3.0 to 3.6 V	3.0 to 3.6 V				
Power consumption	(Тур.)	540mW (@ 3.3 V, 50 MHz)					376mW (@ 3.3 V, 40 MHz)
Package		144-pin plastic LQFP (20	× 20 mm)	144-pin plastic LQFP (20 161-pin plastic FGBA (13	× 20 mm) 8 × 13 mm)		100-pin plastic LQFP (14 \times 14 mm)

Note Number of external interrupts that can be used to release STOP mode



					(2/11)		
		V850	E/IA1	V850E/IA2			
lte	em	μPD703116	μPD70F3116	μPD703114	µPD70F3114		
CPU core		V850E1		V850E1			
CPU performance (D	Ohrystone)	62MIPS (@ 50 MHz)		50MIPS (@ 40 MHz)			
Internal ROM		256 KB (mask ROM)	256 KB (flash memory)	128 KB (mask ROM)	128 KB (flash memory)		
Internal RAM		10 KB		6 KB			
External	Address bus	24 bits		22 bits			
bus interface	Data bus	16 bits		16 bits			
	Programmable waits	0 to 7		0 to 7			
Interrupt sources		External: 20 (14) ^{Note} Internal: 46		External: 16 (12) ^{Note} External: 42			
DSP function	32×32→64	0.02 to 0.04µs (@ 50 MHz)		0.025 to 0.05µs (@ 40 MHz)			
	32×32+32→32	0.06μs (@ 50 MHz)		0.075μs (@ 40 MHz)			
	16×16→32	_		_			
	16×16+32→32	_		_			
Timer/counter (RPU)		16-bit 3-phase sine wave PWM timer × 2 ch 16-bit encoder counter/timer × 2 ch 16-bit timer/counter × 2 ch 16-bit timer/event counter × 1 ch 16-bit interval timer × 1 ch		16-bit 3-phase sine wave PWM timer × 2 ch 16-bit encoder counter/timer × 1 ch 16-bit timer/counter × 2 ch 16-bit timer/counter × 1 ch 16-bit interval timer × 1 ch			
Serial interface	CSI	2 ch		1 ch			
(SIO)	CSI/I ² C	-		-			
	CSI/UART	—		1 ch			
	UART	3 ch		1 ch			
	Dedicated BRG	4 ch		3 ch			
A/D converter		8 ch (10-bit resolution), 2 units		6 ch (10-bit resolution): A/D converter 0, 8 ch (10-bit resolution): A/D converter 1			
DMA controller		4 ch		4 ch			
Real-time output por	rt			-			
Ports	I/O	75		47			
	Input	8		6			
Other peripheral I/O	functions	Memory access control function (SRAM, ROM connectable)		Memory access control function (SRAM, ROM connectable)			
Power save function		HALT, IDLE, STOP		HALT, IDLE, STOP			
Operating frequency		4 to 50 MHz		4 to 40 MHz			
Power supply voltage	e	Internal unit: 3.3 V, A/D converter: 5 V, external pin: 5 V		5 V (Internal unit: 3.3 V, A/D converter: 5 V, external pin: 5 V) (On-chip regulator)			
Power consumption	(Тур.)	630 mW (For internal unit: 3.3 V, extern	nal pin: 5 V, 50 MHz)	440mW			
Package		144-pin plastic LQFP (20 × 20 mm)		100-pin plastic LQFP (14 × 14 mm)			

 $\ensuremath{\textbf{Note}}$ Number of external interrupts that can be used to release STOP mode

						(3/11			
		V850E/MS1							
ł	tem	μPD703100-40	µPD703100-33	μPD703101-33	µPD703102-33	μPD70F3102-33			
CPU core		V850E	V850E						
CPU performance (Dhrystone)			43 MIPS (@ 33 MHz)					
Internal ROM		None		96 KB (mask ROM)	128 KB (mask ROM)	128 KB (flash memory)			
Internal RAM		4 KB							
External	Address bus	24 bits							
bus interface	Data bus	16 bits							
	Programmable waits	0 to 7							
Interrupt sources		External: 25 (1) ^{Note} Internal: 47							
DSP function	32×32→64	0.025 to 0.05µs (@ 40 MHz)	0.03 to 0.06µs (@ 33 MHz)						
	32×32+32→32	0.075μs (@ 40 MHz)	0.09µs (@ 33 MHz)						
	16×16→32	-	1						
	16×16+32→32	-							
Timer/counter (RPU)		16-bit timer/event counter × 6 ch 16-bit interval timer × 2 ch							
Serial interface	CSI	2 ch							
(SIO)	CSI/I ² C	_							
	CSI/UART	2 ch							
	UART	-							
	Dedicated BRG	3 ch							
A/D converter		8 ch (10-bit resolution)							
DMA controller		4 ch							
Real-time output po	ort	-	-						
Ports	I/O	114							
	Input	9	9						
Other peripheral I/C) functions	Memory access control function (EDO DRAM, SRAM, page ROM, etc., directly connectable)							
Power save function	า	HALT, IDLE, STOP							
Operating frequency		2 to 40 MHz	2 to 33 MHz						
Power supply voltage		Internal unit: 3.3 V, A/D conve External pin: 5 V	rter: 5 V						
Power consumption	н (Тур.)	540mW (@ 40 MHz)	430mW (@ 33 MHz)						
Package		144-pin plastic LQFP (20 × 20 mm)							

Note Number of external interrupts that can be used to release STOP mode



							(4/11)		
			V850E/MS2						
Ite	em	μPD703100A-40	μPD703100A-33	μPD703101A-33	μPD703102A-33	μPD70F3102A-33	μPD703130		
CPU core		V850E	ľ		l.		V850E		
CPU performance ([Ohrystone)	-		43MIPS (@ 33 MHz)			_		
Internal ROM	,	None		96 KB (mask ROM)	128 KB (mask ROM)	128 KB (flash memory)	None		
Internal RAM		4 KB					4 KB		
External	Address bus	24 bits					24 bits		
bus interface	Data bus	16 bits					16 bits		
	Programmable waits	0 to 7					0 to 7		
Interrupt sources		External: 25 (1) ^{Note} Internal: 47					External: 10 (1) ^{Note} Internal: 35		
DSP function	32×32→64	0.025 to 0.05µs (@ 40 MHz)	0.03 to 0.06µs (@ 33 MH	łz)			0.03 to 0.06µs (@ 33 MHz)		
	32×32+32→32	0.075μs (@ 40 MHz)	0.09μs (@ 33 MHz)				0.09μs (@ 33 MHz)		
	16×16→32	-							
	16×16+32→32								
Timer/counter (RPU)		16-bit timer/event counter 16-bit interval timer × 2 ch	16-bit timer/ event counter × 4 ch 16-bit interval timer × 2 ch						
Serial interface	CSI	2 ch	2 ch						
(SIO)	CSI/I ² C	-							
	CSI/UART	2 ch	2 ch						
	UART	-	-						
	Dedicated BRG	3 ch					2 ch		
A/D converter		8 ch (10-bit resolution)	4 ch (10-bit resolution)						
DMA controller		4 ch	4 ch						
Real-time output por	t		-						
Ports	I/O	114					76		
	Input	9					5		
Other peripheral I/O functions		Memory access control f (EDO DRAM, SRAM, page	Memory access control function (EDO DRAM, SRAM, page ROM, etc., directly connectable)						
Power save function		HALT, IDLE, STOP					HALT, IDLE, STOP		
Operating frequency		2 to 40MHz	2 to 33MHz				10 to 33MHz		
Power supply voltage		Internal unit: 3.3 V, A/D co External pin: 3.3 V	Internal unit: 3.3 V, A/D converter: 5 V External pin: 5 V						
Power consumption	(Тур.)	330mW (@ 40 MHz)	270mW (@ 33 MHz)				381mW (@ 33 MHz)		
Package		144-pin plastic LQFP (20 × 20 mm)	144-pin plastic LQFP (20 157-pin plastic FBGA (14	0 × 20 mm) 4 × 14 mm)			100-pin plastic LQFP (14 × 14 mm)		

 $\ensuremath{\textbf{Note}}$ Number of external interrupts that can be used to release STOP mode

					(5/11				
		\\	/850ES/SA2	V	V850ES/SA3				
	Item	μPD703201/ μPD70F3201/ μPD703204/ μPD μPD703201Y μPD70F3201Y μPD703204Y μPD							
CPU core		V850ES							
CPU performance	(Dhrystone)	21 MIPS (@ 17 MHz)/16 MIPS (0	@ 13.5 MHz)						
Internal ROM		256 KB (mask ROM)	256 KB (flash memory)	256 KB (mask ROM)	256 KB (flash memory)				
Internal RAM		16 KB							
External Address bus		22 bits	22 bits 24 bits						
bus interface	Data bus	8/16 bits							
	Programmable waits	0 to 7							
Interrupt sources	-	External: 8 (8) ^{Note 1} Internal 30 (Y products: 31)		External: 8 (8) ^{Note 1} Internal: 31 (Y products: 32)					
DSP function	32×32→64	0.24 to 0.29µs (@ 17 MHz)							
	32×32+32→32	0.35µs (@ 17 MHz)	 0.35µs (@ 17 MHz)						
	16×16→32	0.06 to 0.12µs (@ 17 MHz)							
	16×16+32→32	0.18μs (@ 17 MHz)							
Timer/counter (RPU)		16-bit timer/event counter × 2 ch 8-bit timer/event counter × 4 ch (usable as 16-bit timer/event counter × 2 ch)							
Serial interface	CSI	2 ch		3 ch					
(SIO)	CSI/I ² C ^{Note 2}	1 ch		1 ch					
	CSI/UART	1 ch		1 ch					
	UART	1 ch		1 ch					
	Dedicated BRG	2 ch (UART-dedicated)		2 ch	2 ch				
A/D converter		12 ch (10-bit resolution)		16 ch (10-bit resolution)					
DMA controller		4 ch							
Real-time output p	ort	-							
Ports	I/O	68		84	84				
	Input	14		18	18				
Other peripheral I/	O functions	Real-time counter (for watch): 1 ch Watchdog timer: 1 ch							
Power save function	n	HALT, IDLE, STOP							
Operating frequency		When using main clock: 2 to 17 MHz (@ 2.4 V)/2 to 13.5 MHz (@ 2.3 V) When using subclock: 32.768 kHz (only real-time counter operating)							
Power supply volta	age	2.3 to 2.7 V (@ 17 MHz)/2.2 to 2.7 V (@ 13.5 MHz)							
Power consumption	n (Typ.)	When using main clock: 30 mW*	(@ 2.5 V, 17 MHz)						
Package		100-pin plastic LQFP (14 × 14 mr	100-pin plastic LQFP (14 × 14 mm) 121-pin plastic FBGA (12 × 12 mm)						

 $\ensuremath{\textbf{Notes1}}$. Number of external interrupts that can be used to release STOP mode

2. Only Y products have an on-chip l²C bus interface. $CSI/l^2C: \mu PD703201Y, 703204Y, 70F3201Y, 70F3204Y$



								(6/11)		
					V850/SA1	1				
I	tem	μPD703014A/ μPD703014AY	μPD703014B/ μPD703014BY	μPD703015A/ μPD703015AY	μPD703015B/ μPD703015BY	μPD70F3015B/ μPD70F3015BY	μPD703017A/ μPD703017AY	μPD70F3017A/ μPD70F3017AY		
CPU core		V850								
CPU performance	(Dhrystone)	23MIPS (@ 20 MHz)	/19MIPS (@ 17 MHz)							
Internal ROM		64 KB 128 K (mask ROM) (mask		128 KB (mask ROM)		128 KB (flash memory)	256 KB (mask ROM)	256 KB (flash memory)		
Internal RAM		4 KB		·		•	8 KB			
External	Address bus	22 bits								
bus interface	Data bus	16 bits								
	Programmable waits	0 to 3								
Interrupt sources		External: 9 (6) ^{Note 1} Internal: 22								
DSP function	32×32→64	-								
	32×32+32→32	-								
	16×16→32	0.05 to 0.10μs (@ 20 MHz)								
	16×16+32→32	0.15µs (@ 20 MHz)								
Timer/counter (RPU)		16-bit timer/event counter × 2 ch 8-bit timer/event counter × 4 ch (usable as 16-bit timer/event counter × 2 ch)								
Serial interface	CSI	1 ch								
(SIO)	CSI/I ² CNote 2	1 ch								
	CSI/UART	1 ch								
	UART	1 ch								
	Dedicated BRG	2 ch (UART-dedicated)								
A/D converter		12 ch (10-bit resolution)								
DMA controller		3 ch (only for internal RAM↔on-chip peripheral I/O)								
Real-time output po	prt	8-bit × 1 ch or 4-bit × 2 ch								
Ports	I/O	72								
	Input	13								
Other peripheral I/O functions		Watch timer: 1 ch Watchdog timer: 1 ch								
Power save functio	n	HALT, IDLE, STOP								
Operating frequency		Using main clock: 2 to 20 MHz (@ 3.3 V)/2 to 17 MHz (@ 3 V) Using subclock: 32.768 kHz								
Power supply voltage		3.0 to 3.6 V (@ 20 M	Hz)/2.7 to 3.6 V (@ 17	MHz)						
Power consumption	п (Тур.)	Using main clock: 66	mW (@ 3.3 V, 20 MHz)/56 mW (@ 3.3 V, 17 I	ИНz)	Using main clock: 105 mW(@ 3.3 V, 20 MHz)/ 99 mW (@ 3.3 V, 17 MHz)	Using main clock: 66 mW (@ 3.3 V, 20 MHz)/ 56 mW (@ 3.3 V, 17 MHz)	Using main clock: 105 mW (@ 3.3 V, 20 MHz)/ 99 mW (@ 3.3 V, 17 MHz)		
Package		100-pin plastic LQFP (14 × 14 mm) ^{Note 3} 121-pin plastic FBGA (12 × 12 mm) ^{Note 4}								

Notes1. Number of external interrupts that can be used to release STOP mode

2. Only Y products have an on-chip l^2C bus interface.

CSI/I²C : µPD703014AY, 703014BY, 703015AY, 703015BY, 703017AY, 70F3015BY, 70F3017AY

CSI : µPD703014A, 703014B, 703015A, 703015B, 703017A, 70F3015B, 70F3017A

3. μPD703014B, 703014BY, 703015B, 703015BY, 703017A, 703017AY, 70F3015B, 70F3015BY, 70F3017A, 70F3017AY

4. μPD703014A, 703014AY, 703015A, 703015AY, 703017A, 703017AY, 70F3017A, 70F3017AY

							(7/11)					
		V850/SV1										
lt	em	μPD703041/ μPD703041Υ	μРD703039/ μPD703039Y	μPD703040/ μPD703040Υ	μPD70F3040/ μPD70F3040Y	μΡD703038/ μΡD703038Y	μPD70F3038/ μPD70F3038Y					
CPU core		V850										
CPU performance (Dhrystone)	23 MIPS (@ 20 MHz)/18	MIPS (@ 16 MHz)									
Internal ROM		192 KB (mask ROM)	256 KB (mask ROM)		256 KB (flash memory)	384 KB (mask ROM)	384 KB (flash memory)					
Internal RAM		8 KB 16 KB										
External	Address bus	22 bits										
bus interface	Data bus	16 bits										
	Programmable waits	0 to 3										
Interrupt sources		External: 9 (6) ^{Note 1} Internal: 43 (Y products:	44)									
DSP function	32×32→64	-										
	32×32+32→32	-	_									
	16×16→32	0.05 to 0.10µs (@ 20 MH	0.05 to 0.10us (@ 20 MHz)									
	16×16+32→32	0.15µs (@ 20 MHz)										
Timer/counter (RPU)		24-bit timer/event counter × 2 ch 16-bit timer/event counter × 2 ch 8-bit timer/event counter × 8 ch (usable as 16-bit timer/event counter × 4 ch)										
Serial interface	CSI	1 ch										
(SIO)	CSI/I ² C ^{Note 2}	2 ch										
	CSI/UART	2 ch										
	UART	-										
	Dedicated BRG	3 ch										
A/D converter		16 ch (10-bit resolution)										
DMA controller		6 ch (only for internal RAM↔on-chip peripheral I/O)										
Real-time output po	rt	8-bit × 2 ch or 4-bit × 4 cl	ı									
Ports	I/O	135										
	Input	16										
Other peripheral I/O	functions	Vsync/Hsync separator										
		Watch timer: 1 ch Watchdog timer: 1 ch PWM: 4 ch (12 to 16-bit resolution)										
Power save function	1	HALT, IDLE, STOP										
Operating frequency		4 to 20 MHz (@ 3.3 V)/4 to 16 MHz (@ 3 V)										
Power supply voltag	je	3.1 to 3.6 V (@ 20 MHz)/	2.7 to 3.6 V (@ 16 MHz)									
Power consumption	(Тур.)	82 mW (@ 3.3 V, 20 MH:	z)/72 mW (@ 3.3 V, 16 MH:	z)	148 mW (@ 3.3 V, 20 MHz)/ 132 mW (@ 3.3 V, 16 MHz)	82 mW (@ 3.3 V, 20 MHz) 72 mW (@ 3.3 V. 16 MHz)	148 mW (@ 3.3 V, 20 MHz) 132 mW (@ 3.3 V, 16 MHz)					
Package		176-pin plastic LQFP (24 × 24 mm)	176-pin plastic LQFP (24 × 24 mm) 180-pin plastic FBGA (13 × 13 mm) 180-pin plastic FBGA (13 × 13 mm) 180-pin plastic FBGA (13 × 13 mm)									

Notes1. Number of external interrupts that can be used to release STOP mode

2. Only Y products have an on-chip I^2C bus interface.

CSI/I²C : µPD703038Y, 703039Y, 703040Y, 703041Y, 70F3038Y, 70F3040Y

CSI : µPD703038, 703039, 703040, 703041, 70F3038, 70F3040

Caution The maximum operating frequency of the $l^2 C$ bus interface is 17 MHz.



						(8/11)
		V850/SC1	V850/SC2	V850	D/SC3	V850/SC1, V850/SC2, V850/SC3
lte	em	μPD703068Y	["] РD703069Ү	µРD703088Y	μPD703089Y	μPD70F3089Y
CPU core		V850	V850	V850		V850
CPU performance (E	Ohrvstone)	23MIPS (@ 20 MHz)	21MIPS (@ 19 MHz)	18MIPS (@ 16 MHz)		23MIPS (@ 20 MHz)
Internal ROM		512 KB (mask ROM)	512 KB (mask ROM)	512 KB (mask ROM)		512 KB (flash memory)
Internal RAM		24 KB	24 KB	24 KB		24 KB
External	Address bus	22 bits	22 bits	22 bits		22 bits
bus interface	Data bus	16 bits	16 bits	16 bits		16 bits
	Programmable waits	0 to 3	0 to 3	0 to 3		0 to 3
Interrupt sources		External: 12 (9) ^{Note} Internal: 39	External: 12 (9) ^{Note} Internal: 41	External: 12 (9) ^{Note} Internal: 43	External: 12 (9) ^{Note} Internal: 46	External: 12 (9) ^{Note} Internal: 46
DSP function	32×32→64	-	-	-		-
	32×32+32→32	-	-	-		_
	16×16→32	0.05 to 0.10µs (@ 20 MHz)	0.053 to 0.106µs (@ 19 MHz)	0.06 to 0.12µs (@ 16 MHz)		0.05 to 0.10µs (@ 20 MHz)
	16×16+32→32	0.15µs (@ 20 MHz)	0.159µs (@ 19 MHz)	0.18µs (@ 16 MHz)		0.15µs (@ 20 MHz)
Timer/counter (RPU)		16-bit timer/ event counter × 10 ch	16-bit timer/ event counter × 10 ch	16-bit timer/event counter × 10 ch		16-bit timer/ event counter × 10 ch
Serial interface	CSI	2 ch	2 ch	2 ch		2 ch
(SIO)	CSI/I ² C	2 ch	2 ch	2 ch		2 ch
	CSI/UART	2 ch	2 ch	2 ch		2 ch
	UART	2 ch	2 ch	2 ch		2 ch
	Dedicated BRG	5 ch	5 ch	5 ch		5 ch
A/D converter		12 ch (10-bit resolution)	12 ch (10-bit resolution)	12 ch (10-bit resolution)		12 ch (10-bit resolution)
DMA controller		$ \begin{array}{l} \mbox{6 ch (only for internal RAM} \\ \leftarrow \mbox{on-chip peripheral I/O} \end{array} $	6 ch (only for internal RAM \leftrightarrow on-chip peripheral I/O)	6 ch (only for internal RAM↔on-chip peripheral I/O)		6 ch (only for internal RAM \leftrightarrow on-chip peripheral I/O)
Real-time output por	ť		-	-		-
Ports	I/O	112	112	112		112
	Input	12	12	12		12
Other peripheral I/O	functions		IEBus (simple version): 1 ch	FCAN : 1 ch	FCAN : 2 ch	IEBus (simple version): 1 ch/FCAN: 2 ch
		Watch timer: 1 ch Watchdog timer: 1 ch	Watch timer: 1 ch Watchdog timer: 1 ch	Watch timer: 1 ch Watchdog timer: 1 ch		Watch timer: 1 ch Watchdog timer: 1 ch
Power save function		HALT, IDLE, STOP	HALT, IDLE, STOP	HALT, IDLE, STOP		HALT, IDLE, STOP
Operating frequency		Using main clock: 4 to 20 MHz (@ 5 V) Using subclock: 32.768 kHz	Using main clock: 4 to 19 MHz (@ 5 V) Using subclock: 32.768 kHz	Using main clock: 4 to 16 MHz (@ 5 V) Using subclock: 32.768 kHz		Using main clock: 4 to 20 MHz (@ 5 V) Using subclock: 32.768 kHz
Power supply voltage		3.5 to 5.5 V (A/D converter: 4.5 to 5.5 V)	3.5 to 5.5 V (A/D converter: 4.5 to 5.5 V)	3.5 to 5.5 V (A/D converter: 4.5 to 5.5 V)		4.0 to 5.5 V (A/D converter: 4.5 to 5.5 V)
Power consumption	(Тур.)	Using main clock: 125 mW* (@ 5 V, 20 MHz)	Using main clock: 120 mW* (@ 5 V, 19 MHz)	Using main clock: 110 mW* (@	2 5 V, 16 MHz)	Using main clock: 150 mW* (@ 5 V, 20 MHz)
Package		144-pin plastic LQFP (20 × 20 mm)	144-pin plastic LQFP (20 × 20 mm)	144-pin plastic LQFP (20 × 20 mm)		144-pin plastic LQFP (20 × 20 mm)

Note Number of external interrupts that can be used to release STOP mode ${\it Remark}$ Values with * are target values.

										(9/11	
			V850/SF1		V850/SB1						
Item		μPD703078Y	µPD703079Y	µPD70F3079Y	μΡD703031A/ μΡD703031AY	μPD703033A/ μPD703033AY	μPD70F3033A/ μPD70F3033AY	μPD703030A/ μPD703030AY	μPD703032A/ μPD703032AY	μPD70F3032A/ μPD70F3032AY	
CPU core		V850	V850		V850						
CPU performance	(Dhrystone)	18MIPS (@ 16 N	ЛНz)		23MIPS (@ 20	MHz)					
Internal ROM		256 KB (mask ROM)		256 KB (flash memory)	128 KB (mask ROM)	256 KB (mask ROM)	256 KB (flash memory)	384 KB (mask ROM)	512 KB (mask ROM)	512 KB (flash memory)	
Internal RAM		16 KB		1	12 KB	12 KB 16 KB 20 KB 24 KB					
External Address bus		22 bits			22 bits						
bus interface	Data bus	16 bits			16 bits						
	Programmable waits	0 to 3	0 to 3 0 to 3								
Interrupt sources	_	External: 9 (6) ^{Note 1} Internal: 32	External: 9 (6) ^N Internal: 35	lote 1	External: 9 (6) ^{NG} Internal: 30 (Y p	ore 1 products: 31)					
DSP function	32×32→64	-	1		-						
	32×32+32→32	-		-							
	16×16→32	0.06 to 0.12µs (@ 16 MHz)			0.05 to 0.10us (@ 20 MHz)						
	16×16+32→32	0.18µs (@ 16 MHz)		0.15µs (@ 20 MHz)							
Timer/counter (RPU)		16-bit timer/even	16-bit timer/event counter × 8 ch		16-bit timer/event counter × 2 ch 8-bit timer/event counter × 4 ch (usable as 16-bit timer/event counter × 2 ch) 8-bit timer × 2 ch (usable as 16-bit timer × 1 ch)						
Serial interface	CSI	1 ch	1 ch		1 ch						
(SIO)	CSI/I ² C ^{Note 2}	1 ch		2 ch							
	CSI/UART	2 ch		2 ch							
	UART	_			-						
	Dedicated BRG	3 ch	3 ch			3 ch					
A/D converter		12 ch (10-bit resolution)			12 ch (10-bit resolution)						
DMA controller		6 ch (only for internal RAM↔on-chip peripheral I/O)		6 ch (only for internal RAM↔on-chip peripheral I/O)							
Real-time output po	ort	-			8 bits \times 1 or 4 bits \times 2						
Ports	I/O	72			71						
	Input	12			12						
Other peripheral I/0	O functions	FCAN : 1 ch	FCAN : 2 ch								
		Watch timer : 1 o Watchdog timer	ch : 1 ch		Watch timer: 1 ch Watchdog timer: 1 ch						
Power save functio	'n	HALT, IDLE, ST	OP		HALT, IDLE, STOP						
Operating frequency		Using main clock Using subclock:	k: 4 to 16 MHz (@ 32.768 kHz	2 5 V)	Using main clock: 2 to 20 MHz (@ 5 V) Using subclock: 32.768 kHz						
Power supply volta	ge	4.0 to 5.5 V (A/D (@ 16 MHz)	converter: 4.5 to	5.5 V)	4.0 to 5.5 V (A/D converter: 4.5 to 5.5 V)						
Power consumption	n (Typ.)	Using main clock 125 mW (flash n	k: 75 mW (mask F nemory)(@ 5 V, 1	ROM)/ 6 MHz)	Using main cloc 125 mW (@ 5 V	k: (, 20 MHz)	Using main clock: 165 mW (@ 5 V, 20 MHz)	Using main clo 125 mW (@ 5 V	ck: /, 20 MHz)	Using main clock: 165 mW (@ 5 V, 20 MHz)	
Package		100-pin plastic LQFP (14 × 14 mm) 100-pin plastic QFP (14 × 20 mm)		100-pin plastic LQFP (14 × 14 mm) 100-pin plastic QFP (14 × 20 mm) 100-pin plastic QFP (14 × 20 mm) 100-pin plastic QFP (14 × 20 mm))				

Notes1. Number of external interrupts that can be used to release STOP mode

2. Only Y products have an on-chip I^2C bus interface.

CSI//²C : μPD703030AY, 703031AY, 703032AY, 703033AY, 703078Y, 703079Y, 70F3032AY, 70F3033AY, 70F3079Y CSI : μPD703030A, 703031A, 703032A, 703033A, 70F3032A, 70F3033A



		(10/11)								
lt	em	μΡD703034A/ μΡD703034AY	μΡD703035A/ μΡD703035AY	μPD70F3035A/ μPD70F3035AY	μPD703036A/ μPD703036AY	μPD703037A/ μPD703037AY	μΡD70F3037A/ μΡD70F3037AY			
CPU core		V850				•				
CPU performance (Dhrystone)	15MIPS (@ 13 MHz)								
Internal ROM		128 KB (mask ROM)	256 KB (mask ROM)	256 KB (flash memory)	384 KB (mask ROM)	512 KB (mask ROM)	512 KB (flash memory)			
Internal RAM	_	12 KB	16 KB		20 KB	24 KB				
External	Address bus	22 bits								
bus interface	Data bus	16 bits								
	Programmable waits	0 to 3								
Interrupt sources		External: 9 (6) ^{Note 1} Internal: 32 (Y products:	33)							
DSP function	32×32→64	-								
	32×32+32→32	-								
	16×16 →32	0.077 to 0.154µs (@ 13 l	MHz)							
	16×16+32→32	0.231µs (@ 13 MHz)								
Timer/counter (RPU)		16-bit timer/event counter × 2 ch 8-bit timer/event counter × 4 ch (usable as 16-bit timer/event counter × 2 ch) 8-bit timer × 2 ch (usable as 16-bit timer × 1 ch)								
Serial interface	CSI	1 ch								
(SIO)	CSI/I ² C ^{Note 2}	2 ch								
	CSI/UART	2 ch								
	UART	_								
	Dedicated BRG	3 ch								
A/D converter		12 ch (10-bit resolution)								
DMA controller		6 ch (only for internal RAM↔on-chip peripheral I/O)								
Real-time output po	rt	8 bits × 1 or 4 bits × 2								
Ports	I/O	71								
	Input	12								
Other peripheral I/C	functions	IEBus (simple version)								
		Watch timer: 1 ch Watchdog timer: 1 ch								
Power save function	1	HALT, IDLE, STOP								
Operating frequency		Using main clock: 2 to 13 MHz (@ 5 V) Using subclock: 32.768 kHz								
Power supply voltage		4.0 to 5.5 V (A/D convert	er: 4.5 to 5.5 V)							
Power consumption	(Тур.)	Using main clock: 75 mW (@ 5 V, 13 MHz)	1	Using main clock: 125 mW (@ 5 V, 13 MHz)	Using main clock: 75 mW (@ 5 V, 13 MHz)		Using main clock: 125 mW (@ 5 V, 13 MHz)			
Package		100-pin plastic LQFP (14 100-pin plastic QFP (14 >	× 14 mm) : 20 mm)		100-pin plastic QFP (14 × 20 mm)					

Notes1. Number of external interrupts that can be used to release STOP mode

2. Only Y products have an on-chip I^2C bus interface.

CSI/2C : µPD703034AY, 703035AY, 703036AY, 703037AY, 70F3035AY, 70F3037AY CSI : µPD703034A, 703035A, 703036A, 703037A, 70F3035A, 70F3037A

						(11/11					
		V853									
I	tem	μPD703003A	μPD703004A	μPD703025A	#PD70F3003A	μPD70F3025A					
CPU core		V850	•								
CPU performance	(Dhrystone)	38MIPS (@ 33 MHz)									
Internal ROM		128 KB (mask ROM)	96 KB (mask ROM)	256 KB (mask ROM)	128 KB (flash memory)	256 KB (flash memory)					
Internal RAM		4 KB		8 KB	4 KB	8 KB					
External	Address bus	20 bits	20 bits								
bus interface	Data bus	16 bits	16 bits								
	Programmable waits	0 to 3									
Interrupt sources		External: 17 (1) ^{Note} Internal: 32									
DSP function	32×32→64	-									
	32×32+32→32	-	_								
	16×16→32	0.03 to 0.06us (@.33.MHz)									
	16×16+32→32	0.00 to 0.00µs (@ 33 MHz)									
Timer/counter (RPU)		16-bit timer/event counter × 4 ch 16-bit timer × 1 ch									
Serial interface	CSI	2 ch									
(SIO)	CSI/I ² C	-									
	CSI/UART	2 ch									
	UART	_									
	Dedicated BRG	3 ch									
A/D converter		8 ch (10-bit resolution)									
DMA controller		-									
Real-time output po	ort										
Ports	1/0	67									
	Input	8									
Other peripheral I/O functions		PWM: 2 ch (8/9/10/12-bit resolution) D/A converter: 2 ch									
Power save function	n	HALT, IDLE, STOP									
Operating frequency		5 to 33 MHz (@ 5 V)									
Power supply voltage	ge	4.5 to 5.5V									
Power consumption	т (Тур.)	365 mW (@ 5 V, 33 MHz)		450 mW (@ 5V, 33 MHz)	425 mW (@ 5 V, 33 MHz)	480 mW (@ 5 V, 33 MHz)					
Package		100-pin plastic LQFP (14 × 14 mm)									

Note Number of external interrupts that can be used to release STOP mode



Development Tools (1/3)

Software tools

Product Name					
Software package	SP850				
C compiler	CA850 ^{Note 1}				
Device file	DF703xxx ^{Note 1}				
Project Manager	PM ^{Notes 1, 2}				
Integrated debugger	ID850 ^{Note 1}				
System simulator	SM850 ^{Note 1}				
Real-time OS	RX850, RX850 Pro				
Task debugger	RD850, RD850 Pro ^{Note 3}				
System performance analyzer	AZ850 ^{Note 1}				
Middleware	AP703000-Bxxx, AP703100-Bxxx				

Notes 1. Packaged in SP850

2. Included with CA850

3. Included with RX850, RX850 Pro

Remark For details, refer to the V800 Series[™] Development Environment Pamphlet (U10782E).

Development Tools (2/3)

■Hardware tools

Target	Device	In-Circuit Emulator				
Device Name	Package	Main Unit	Emulation Board			
V850E/MA1	144-pin plastic LQFP (20 × 20 mm) 161-pin plastic FBGA (13 × 13 mm)	_ IE-V850E-MC-A	IE-703107-MC-EM1 IE-703107-MC-EM1 + CSSOCKET161A1413N01S1 (under development) ^{Note 1} LSPACK161A1413N01 (under development) ^{Note 1}			
V850E/MA2	100-pin plastic LQFP (14 × 14 mm)	-	IE-703107-MC-EM1 + VP-V850E/MA1-MA2 (under development) ^{Note 2}			
V850E/IA1	144-pin plastic LQFP (20 × 20 mm)	IE-V850E-MC	IE-703116-MC-EM1			
V850E/IA2	100-pin plastic LQFP (14 × 14 mm)		IE-703114-MC-EM1			
V850E/MS1 (5V)	144-pin plastic LQFP ($20 \times 20 \text{ mm}$)	IE-703102-MC	IE-703102-MC-EM1			
V850E/MS1 (3.3V)	144-pin plastic LQFP ($20 \times 20 \text{ mm}$)		IE-703102-MC-EM1-A			
	157-pin plastic FBGA (14 × 14 mm)		IE-703102-MC-EM1-A + CSPACK157A1614N01 ^{Note 1} CSICE157A1614N01 ^{Note 1}			
V850E/MS2 (5V)	100-pin plastic LQFP (14 × 14 mm)		IE-703102-MC-EM1 + VP-V850E/MS1-MS2 ^{Note 2}			
V850/SA1	100-pin plastic LQFP (14 × 14 mm)	IE-703002-MC	IE-703017-MC-EM1			
	121-pin plastic FBGA (12 × 12 mm)		IE-703017-MC-EM1 + CSPACK121A1312N02 ^{Note 1} CSICE121A1312N02 ^{Note 1}			
V850/SB1, V850/SB2	100-pin plastic LQFP (14 \times 14 mm)		IE-703037-MC-EM1			
	100-pin plastic QFP (14 × 20 mm)		IE-703037-MC-EM1 + NEXB-100SD/RB ^{Note 1}			
V850/SV1	176-pin plastic LQFP (24×24 mm)		IE-703040-MC-EM1			
	180-pin plastic FBGA (13 × 13 mm)		IE-703040-MC-EM1 + CSSOCKET180A1513N01N ^{Note 1} CSSOCKET180A1513N01S01 ^{Note 1} EXC-180A/SV1 ^{Note 1}			
V850/SF1	100-pin plastic LQFP (14 \times 14 mm)]	IE-703079-MC-EM1			
	100-pin plastic QFP (14 × 20 mm)		IE-703079-MC-EM1 + SWEX100SD/GF-N17D ^{Note 1} NQPACK100RB ^{Note 1} YQPACK100RB ^{Note 1} HQPACK100RB ^{Note 1} YQSOCKET100RBN ^{Note 1} YQGUIDE ^{Note 1}			
V850/SC1, V850/SC2, V850/SC3	144-pin plastic LQFP (20 × 20 mm)	1	IE-703089-MC-EM1			
V853	100-pin plastic LQFP (14 × 14 mm)		IE-703003-MC-EM1			

Notes 1. Tokyo Eletech Corp. 2. Naito Densei Machida Mfg. Co., Ltd.

Remarks 1. The following parts are required as common products.

PC interface board :IE-70000-PCI-IF-A or IE-70000-CD-IF-A
 Power supply :IE-70000-MC-PS-B

2. For details, refer to the V800 Series[™] Development Environment Pamphlet (U10782E).



Development Tools (3/3)



• V850E/MA1, V850E/MA2, V850E/IA1, V850E/IA2 hardware tool configuration example

• V850E/MS1, V850E/MS2 hardware tool configuration example





• V850/SA1, V850/SB1, V850/SB2, V850/SV1, V850/SF1, V850/SC1 ,V850/SC2, V850/SC3, V853 hardware tool configuration example



Development environment using in-circuit emulator



Development environment using ROM emulator and evaluation board





Development Environment (2/2)

Development environment using simulator



Software Package (SP850)

Product configuration

The SP850 software package consists of the following software development tools.

•C compiler (CA850)

- •Project Manager (PM)
- •Integrated debugger (ID850)
- •System simulator (SM850)
- •System performance analyzer (AZ850)
- •Device file (DF703xxx)

System Simulator (SM850)

Features

- •Same operability as debugger
- •Target-less evaluation prior to target completion possible
- In addition to the operation of the CPU itself, target system operation including on-chip peripheral unit and interrupt servicing can also be simulated.
- •Pseudo-target system construction and I/O operation are possible through external parts.
- •Data generated by 0/1 logic and timing charts can be input to the program being simulated.
- •Larger number of events than in-circuit emulator
- •Execution speed estimates can be done on the host machine to accurately simulate pipeline operation^{Note}.
- •Construction by user target system users is possible through user open interface.
- •A peripheral I/O register status can be specified and when this status occurs, the system can be made to output an interrupt at the desired timing or transfer data to memory (peripheral I/O register event & action function).

Note The pipeline mode is supported by the V853.

Target devices

V853, V850/SA1, V850/SB1, V850/SB2, V850/SF1, V850E/MS1, V850E/ MA1, V850E/IA1



C Compiler (CA850)

Features

- •Complies with ANSI-C, a C language standard.
- •Supports libraries for embedded systems
- •Compact code size and faster execution speed can be realized through powerful optimization
- •Utilities useful for embedded systems (ROMization processor, etc.)
- •Description of embedded systems in C language (specification of memory allocation and I/O register access) is possible.

Project Manager (PM)

Features

- Project management (management of target chip, source, and environment during debugging is possible.)
- •Automation of series of operations consisting of edit, build, and debug •Integration of Help function
- •Included with C compiler package





Integrated Debugger (ID850)

Features

- Supports object files
- Debugging at source level
- •Debugging using target resources
- Real-time execution on target
- •Event setting according to complex software operation
- •Online help function

Real-Time OSs (RX850, RX850 Pro)

Features

- Comply with global standard (μITRON 3.0 specifications).
 Support power management function.
- •Enable embedding of required functions only (selection of system calls to be used).
- •Support sophisticated task development through task debugger (RD).
- •Support application operation analysis through system performance analyzer (AZ)
- •Inherit attributes of real-time OS of 16-bit V Series and 78K Series

System Performance Analyzer (AZ850)

Features

- •Detection of bugs through system timing errors
- •Detection of bugs due to simultaneous operation of complex tasks
- •Detection/analysis of real-time system execution performance
- •Operation linked to various debuggers



In-Circuit Emulator

Features

- •Realization of high transparency with emulator functions concentrated in a dedicated chip
- •V850 core IE enabling easy product expansion
- •V850E1 core IE enabling high-speed operation
- •Connectable to various personal computers

Task Debuggers (RD850, RD850 Pro)

Features

- •Display detailed information on OS resources such as tasks. •Issue system calls.
- •Display source of referenced tasks.
- •Included with real-time OS (RX850, RX850 Pro)

TCP/IP Software Library (RX-NET) for V850E Products

Product configuration

- •TCP/IP protocol stack
- Applications
- LAN control driver

Features

- RFC-compliant
- Multiprotocol stack
- •Support of numerous socket interfaces/libraries
- •Support of applications as option products
- •Simplified device driver
- Support of NEC real-time OS (RX850 Pro)

Target devices

V850E products

OSEK/VDX Specification-Compliant OS (RX-OSEK850)

Features

- Kernel
 - OSEK/VDX OS Ver. 2.0 specification-compliant

Supports four conformance classes (BCC1, BCC2, ECC1, ECC2).

Communications

OSEK/VDX COM Ver. 2.1 Rev. 1 specification-compliant

Supports three conformance classes (CCC1, CCC2, CCC3).

Configurator

Configurator simplifying construction of system information (OIL850)

- OIL Ver. 2.0-compliant format supported for configuration files
- Task debugger (RD-OSEK850)

Task debugger effective for debugging applications that use the RX-OSEK850 included as standard.

RISC Microcontroller Reference Platform (SolutionGear™)

Features

- General-purpose evaluation boards available as development platforms for RISC microcontroller software
- Supported CPU: V850E/MA1
- Global and PC-compatible interfaces provided, including PCI, ISA, PCMCIA, E-IDE, EthernetTM, Serial, Parallel, PS/2, and USB
- Used combined with CPU-independent motherboard (usable in common with VR Series) and any of various CPU boards
- Real-time OS, middleware, and sample drivers are included.
- Development environment of Green Hills Software (evaluation version) provided
- MULTI/PARTNER remote monitor version can be used.
- Reference design information provided



Cooperation with Third Parties

By strengthening its cooperation with third-party companies and creating tool groups that combine the best characteristics of NEC tools and third-party tools, NEC provides a development environment that answers diversified user needs.





V850 Series Website Introduction

For information about the V850 Series and the V850 Series development environment, check out the NEC Microcomputer website.





Product Information

 Product information on the V850 Series, development environments for the V850 Series, and the middleware reference platform can be referenced.

Downloading Development Tools

 Development tools for the V850 Series can be downloaded. Upgrade information is provided.

Downloading Documents

 Documents about the V850 Series and V850 Series development environment can be downloaded.

FAQ

 Answer to questions about the V850 Series development environment are introduced.







IEBus, EEPROM, Solution Gear, V Series, V800 Series, V850 Series, V830 Family, V853, V850/SA1, V850/SB1, V850/SB2, V850/SC1, V850/SC2, V850/SC3, V850/SF1, V850/SV1, V850E/IA1, V850E/IA2, V850E/MA1, V850E/MA2, V850E/MS1, V850E/MS2, V850ES/SA2, V850ES/SA3, and V_R Series are trademarks of NEC Corporation.

TrueSpeech is a trademark of DSP Group, Inc.

- JAVA and all trademarks and logos related to JAVA are trademarks of Sun Microsystems, Inc.
- Windows and Windows NT are either registered trademarks or trademarks of Microsoft Corporation in the United States and/or other countries.

NORTi is a trademark of MiSPO, Inc.

CodeWarrior is a trademark of Metrowerks Corporation.

Green Hills Software and MULTI are trademarks of Green Hills Software, Inc.

WATCHPOINT is a trademark of Sophia Systems Co., Ltd.

Tornado is a trademark of Wind River Systems, Inc.

Virtual ICE is a trademark of Yokogawa Electric Corporation.

Synopsys Eaglei is a trademark of Synopsys, Inc.

TRON stands for The Realtime Operating system Nucleus.

ITRON is an abbreviation of Industrial TRON.

Ethernet is a trademark of Xerox Corporation.

Caution: The I²C bus interface circuit is incorporated in the μ PD703014AY, 703014BY, 703015AY, 703015BY, 70F3015BY, 703017AY, 70F3017AY, 703030AY, 703031AY, 703032AY, 70F3032AY, 703033AY, 70F3033AY, 7053034AY, 703035AY, 70F3035AY, 703036AY, 703037AY, 70F3037AY, 703038Y, 70F3038Y, 703039Y, 703040Y, 70F3040Y, 703041Y, 703068Y, 703069Y, 703078Y, 703079Y, 70F3079Y, 703088Y, 703089Y, 70F3089Y, 703201Y, 70F3201Y, 703204Y, 70F3204Y. Those who use the I²C bus interface can be granted the license below by giving prior notification before ordering the custom code.

Purchase of NEC I²C components conveys a license under the Philips I²C Patent Rights to use these components in an I²C system, provided that the system conforms to the I²C Standard Specification as defined by Philips.



The export of these products from Japan is regulated by the Japanese government. The export of some or all of these products may be prohibited without governmental license. To export or re-export some or all of these products from a country other than Japan may also be prohibited without a license from that country. Please call an NEC sales representative.

- The information in this document is current as of August, 2001. The information is subject to change without notice. For actual design-in, refer to the latest publications of NEC's data sheets or data books, etc., for the most up-to-date specifications of NEC semiconductor products. Not all products and/or types are available in every country. Please check with an NEC sales representative for availability and additional information.
- No part of this document may be copied or reproduced in any form or by any means without prior written consent of NEC. NEC assumes no responsibility for any errors that may appear in this document.
- NEC does not assume any liability for infringement of patents, copyrights or other intellectual property rights of third parties by or arising from the use of NEC semiconductor products listed in this document or any other liability arising from the use of such products. No license, express, implied or otherwise, is granted under any patents, copyrights or other intellectual property rights of NEC or others.
- Descriptions of circuits, software and other related information in this document are provided for illustrative purposes in semiconductor product operation and application examples. The incorporation of these circuits, software and information in the design of customer's equipment shall be done under the full responsibility of customer. NEC assumes no responsibility for any losses incurred by customers or third parties arising from the use of these circuits, software and information.
- While NEC endeavours to enhance the quality, reliability and safety of NEC semiconductor products, customers
 agree and acknowledge that the possibility of defects thereof cannot be eliminated entirely. To minimize
 risks of damage to property or injury (including death) to persons arising from defects in NEC
 semiconductor products, customers must incorporate sufficient safety measures in their design, such as
 redundancy, fire-containment, and anti-failure features.
- NEC semiconductor products are classified into the following three quality grades:

"Standard", "Special" and "Specific". The "Specific" quality grade applies only to semiconductor products developed based on a customer-designated "quality assurance program" for a specific application. The recommended applications of a semiconductor product depend on its quality grade, as indicated below. Customers must check the quality grade of each semiconductor product before using it in a particular application.

- "Standard": Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots
- "Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
- "Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

The quality grade of NEC semiconductor products is "Standard" unless otherwise expressly specified in NEC's data sheets or data books, etc. If customers wish to use NEC semiconductor products in applications not intended by NEC, they must contact an NEC sales representative in advance to determine NEC's willingness to support a given application.

(Note)

(1) "NEC" as used in this statement means NEC Corporation and also includes its majority-owned subsidiaries.
(2) "NEC semiconductor products" means any semiconductor product developed or manufactured by or for NEC (as defined above).

M8E 00.4

For further information, please contact:

NEC Corporation

NEC Building 7-1, Shiba 5-chome, Minato-ku Tokyo 108-8001, Japan Tel: 03-3454-1111 http://www.ic.nec.co.jp/

[North & South America]

NEC Electronics Inc.

2880 Scott Blvd. Santa Clara, CA 95050-2554, U.S.A. Tel: 408-588-6000 800-366-9782 Fax: 408-588-6130 800-729-9288 http://www.necel.com/

NEC do Brasil S.A.

Electron Devices Division Rodovia Presidente Dutra, Km 214 07210-902-Guarulhos-SP Brasil Tel: 011-6462-6810 Fax: 011-6462-6829

[Europe]

NEC Electronics (Europe) GmbH

Oberrather Str. 4 40472 Düsseldorf, Germany Tel: 0211-6503-01 Fax: 0211-6503-327 http://www.ee.nec.de/

Branch The Netherlands

Boschdijk 187a 5612 HB Eindhoven, The Netherlands Tel: 040-2445845 Fax: 040-2444580

Branch Sweden

P.O. Box 134 18322 Taeby, Sweden Tel: 08-6380820 Fax: 08-6380388

NEC Electronics (UK) Limited

Cygnus House, Sunrise Parkway, Linford Wood, Milton Keynes, MK14 6NP, U.K. Tel: 01908-691-133 Fax: 01908-670-290

NEC Electronics (France) S.A.

9, rue Paul Dautier-B.P. 52 78142 Velizy-Villacoublay Cédex France Tel: 01-3067-5800 Fax: 01-3067-5899

Madrid Office

Juan Esplandiu, 15 28007 Madrid, Spain Tel: 091-504-2787 Fax: 091-504-2860

NEC Electronics Italiana s.r.l.

Via Fabio Filzi, 25/A, 20124 Milano, Italy Tel: 02-667541 Fax: 02-66754299

[Asia & Oceania]

NEC Electronics Hong Kong Limited

12/F., Cityplaza 4, 12 Taikoo Wan Road, Hong Kong Tel: 2886-9318 Fax: 2886-9022/9044

Seoul Branch

10F, ILSONG Bldg., 157-37, Samsung-Dong, Kangnam-Ku Seoul, the Republic of Korea Tel: 02-528-0303 Fax: 02-528-4411

NEC Electronics Taiwan Ltd.

7F, No. 363 Fu Shing North Road Taipei, Taiwan, R. O. C. Tel: 02-2719-2377 Fax: 02-2719-5951

NEC Electronics Singapore Pte. Ltd.

238A Thomson Road #12-01/10 Novena Square Singapore 307684 Tel: 253-8311 Fax: 250-3583

Document No. U15412EJ1V0PF00 (1st edition) Date Published February 2002 N CP(K) G02.1